

# 1 W High-Voltage Switchmode Regulator

#### **DESCRIPTION**

The Si9108 high-voltage switchmode regulator is a monolithic BiC/DMOS integrated circuit which contains most of the components necessary to implement a high-efficiency dc/dc converter in ISDN terminals up to 3 watts. A 0.5 mA max supply current makes possible the design of a dc/dc converter with 60 % efficiency at 25 mW, therefore meeting the recommended performance under the CCITT I.430 specifications.

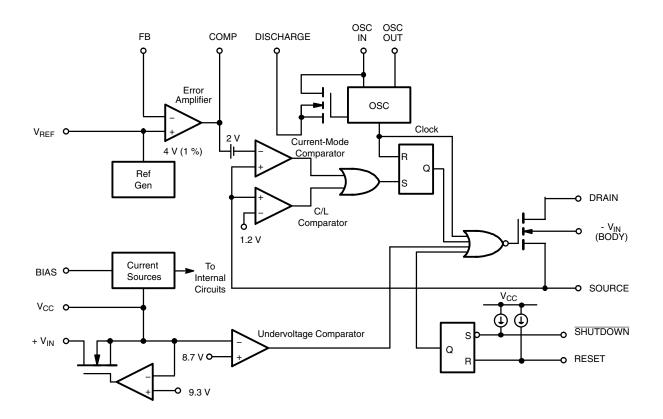
This device may be used with an appropriate transformer to implement isolated flyback power converter topologies to provide single or multiple regulated dc outputs (i.e.,  $\pm$  5 V).

The Si9108 is available in both standard and lead (Pb)-free 16-pin wide-body SOIC, 14-pin plastic DIP and 20-pin PLCC packages which are specified to operate over the industrial temperature range of - 40 °C to 85 °C.

#### **FEATURES**

- CCITT Compatible
- · Current-Mode Control
- Low Power Consumption (less than 5 mW)
- 10 to 120 V Input Range
- 200 V, 250 mA MOSFET
- Internal Start-Up Circuit
- SHUTDOWN and RESET
- Maximum Duty Cycle of 99.9 %

#### **FUNCTIONAL BLOCK DIAGRAM**



Document Number: 70883 S-42038-Rev. B, 15-Nov-04



Parameter		Limit	Unit	
Voltages Referenced to - V <sub>IN</sub> (V <sub>CC</sub> < -	+ V <sub>IN</sub> + 0.3 V)			
V <sub>CC</sub>		15		
+V <sub>IN</sub>		120	V	
V <sub>DS</sub>		200		
$I_D$ (Peak) (300 $\mu$ s pulse, 2 % duty cycle		2	Α	
I <sub>D</sub> (rms)		250	mA	
Logic Inputs (RESET, SHUTDOWN, O	- 0.3 V to V <sub>CC</sub> + 0.3 V	V		
Linear Inputs (FEEDBACK, SOURCE)		- 0.3 V to 7 V	ď	
HV Pre-Regulator Input Current (contin	uous)	5	mA	
Storage Temperature		- 65 to 125		
Operating Temperature		- 40 to 85	°C	
Junction Temperature (T <sub>J</sub> )		150		
	14-Pin Plastic DIP (J Suffix) <sup>b</sup>	750		
Power Dissipation (Package) <sup>a</sup>	16-Pin Plastic Wide-Body SOIC (W Suffix) <sup>c</sup>	900	mW	
20-Pin PLCC (N Suffix) <sup>d</sup>		1400		
	14-Pin Plastic DIP	167		
Thermal Impedance $(\Theta_{JA})$	16-Pin Plastic Wide-Body SOIC	140	°C/W	
	20-Pin PLCC	90		

#### Notes:

- a. Device Mounted with all leads soldered or welded to PC board.
  b. Derate 6 mW/°C above 25 °C.
  c. Derate 7.2 mW/°C above 25 °C.
  d. Derate 11.2 mW/°C above 25 °C.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING RANGE					
Parameter	Limit	Unit			
Voltages Referenced to - V <sub>IN</sub>					
V <sub>CC</sub>	10 V to 13.5 V	V			
+ V <sub>IN</sub>	10 V to 120 V	]			
fosc	40 kHz to 1 MHz				
R <sub>OSC</sub>	25 kΩ to 1 MΩ				
Linear Inputs	0 to V <sub>CC</sub> - 3 V	V			
Digital Inputs	0 to V <sub>CC</sub>	]			

SPECIFICATIONS <sup>a</sup>							
		Test Conditions	Limits				
Parameter	Symbol			Min <sup>c</sup>	Typ <sup>d</sup>	Max <sup>c</sup>	Unit
Reference							
Output Voltage	V <sub>R</sub>	OSC IN = - $V_{IN}$ (OSC Disabled) $R_L = 10 \text{ M}\Omega$	Room	3.92	4.00	4.08	V
Output Impedance <sup>e</sup>	Z <sub>OUT</sub>	OSC IN = - V <sub>IN</sub>	Room	15	300	45	kΩ
Short Circuit Current	I <sub>SREF</sub>	OSC IN = - $V_{IN}$ , $V_{REF}$ = - $V_{IN}$	Room	70	100	130	μΑ
Temperature Stability <sup>e</sup>	T <sub>REF</sub>	OSC IN = - V <sub>IN</sub>	Full		0.25	1.0	mV/°C
Long Term Stability <sup>e</sup>		$t = 1000 \text{ hrs}, T_A = 125 ^{\circ}\text{C}$	Room		5.00	25.00	mV
Oscillator							
Maximum Frequency <sup>e</sup>	f <sub>MAX</sub>	$R_{OSC} = 0$	Room	1	3		MHz
Initial Accuracy	fosc	See Note e	Room	32	40	48	kHz
Voltage Stability	∆f/f	$\Delta f/f = f (13.5 \text{ V}) - f (9.5 \text{ V}) / f (9.5 \text{ V})$	Room		10	15	%
Temperature Coefficient <sup>e</sup>	T <sub>OSC</sub>		Full		200	500	ppm/°C

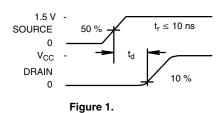


		Test Conditions		Lir	nits		
Parameter	Symbol	Unless Otherwise Specified DISCHARGE = - $V_{IN}$ = 0 V $V_{CC}$ = 10 V, + $V_{IN}$ = 48 V $R_{BIAS}$ = 820 k $\Omega$ , $R_{OSC}$ = 910 k $\Omega$	Temp <sup>b</sup>	Min <sup>c</sup>	Typ <sup>d</sup>	Max <sup>c</sup>	Unit
Error Amplifier							
Feedback Input Voltage	V <sub>FB</sub>	FB Tied to COMP OSC IN = - $V_{IN}$ (OSC Disabled)	Room	3.96	4	4.04	V
Input BIAS Current	I <sub>FB</sub>	OSC IN = - $V_{IN}$ , $V_{FB} = 4 V$	Room		25	500	nA
Open Loop Voltage Gain <sup>e</sup>	A <sub>VOL</sub>	OSC IN = - $V_{IN}$ (OSC Disabled)	Room	60	80		dB
Input Offset Voltage	V <sub>OS</sub>		Room		± 15	± 40	mV
Unity Gain Bandwidth <sup>e</sup>	BW	OSC IN = $-V_{IN}$	Room	0.5	8.0		MH
Dynamic Output Impedance	Z <sub>OUT</sub>		Room		1		kΩ
Output Current	I <sub>OUT</sub>	Source $(V_{FB} = 3.4 \text{ V})$	Room		- 1.2	- 0.32	mA
·		Sink $(V_{FB} = 4.5 V)$	Room	0.05	0.08		111/-
Power Supply Rejection	PSRR	10 V ≤ V <sub>CC</sub> ≤ 13.5 V	Room		70		dB
PWM							
Maximum Duty Cycle	D <sub>MAX</sub>		Room	99.0	99.6	99.9	%
Dead Time			Room		100		ns
Minimum Duty Cycle	D <sub>MIN</sub>		Room			0	%
Minimum Pulse Width Before Pulse Drops Out			Room		110	175	ns
Current Limit							
Threshold Voltage	V <sub>SOURCE</sub>	$R_L$ = 100 $\Omega$ from DRAIN to $V_{CC}$ $V_{FB}$ = 0 $V$	Room	0.8	1.0	1.2	٧
Delay to Output <sup>e</sup>	t <sub>d</sub>	$R_L$ = 100 $\Omega$ from DRAIN to $V_{CC}$ $V_{SOURCE}$ = 1.5 V, See Figure 1	Room		200	300	ns
Input Voltage	+ V <sub>IN</sub>	I <sub>IN</sub> = 10 μA	Room	120			V
Input Leakage Current	+ I <sub>IN</sub>	V <sub>CC</sub> ≥ 10 V	Room			10	μΑ
Pre-Regulator Start-Up Current	I <sub>START</sub>	Pulse Width ≤ 300 μs, V <sub>CC</sub> = 7 V	Room	8	15		m/
V <sub>CC</sub> Pre-Regulator Turn-Off Threshold Voltage	V <sub>REG</sub>	I <sub>PRE-REGULATOR</sub> = 10 μA	Room	7.5	9.3	9.7	
Undervoltage Lockout	V <sub>UVLO</sub>	$R_L = 100 \Omega$ from DRAIN to $V_{CC}$ See Detailed Description	Room	7.0	8.7	9.2	V
V <sub>REG</sub> - V <sub>UVLO</sub>	V <sub>DELTA</sub>		Room	0.25	0.5		
Supply							
Supply Current	I <sub>CC</sub>		Room		0.35	0.5	mA
Bias Current	I <sub>BIAS</sub>		Room		7.5		μΑ
SHUTDOWN Delay	t <sub>SD</sub>	$V_{SOURCE} = -V_{IN}$ , See Figure 2	Room		50	100	
SHUTDOWN Pulse Width	t <sub>SW</sub>		Room	50			1
RESET Pulse Width	t <sub>RW</sub>	See Figure 3	Room	50			ns
Latching Pulse Width SHUTDOWN and RESET Low	t <sub>LW</sub>		Room	25			
Input Low Voltage	V <sub>IL</sub>		Room			2.0	V
Input High Voltage	V <sub>IH</sub>		Room	8.0			
Input Current Input, Voltage High	I <sub>IH</sub>	V <sub>IN</sub> = 10 V	Room		1	5	
Input Current Input, Voltage Low	I <sub>IL</sub>	V <sub>IN</sub> = 0 V	Room	- 35	- 25		μΑ
MOSFET Switch							
Breakdown Voltage	V <sub>BR(DSS)</sub>	I <sub>DRAIN</sub> = 100 μA	Full	200	220		V
Drain-Source On Resistance <sup>9</sup>	r <sub>DS(on)</sub>	I <sub>DRAIN</sub> = 100 mA	Room		5	7	Ω
Drain Off Leakage Current	I <sub>DSS</sub>	V <sub>DRAIN</sub> = 100 V	Room			10	μΑ
Drain Capacitance	C <sub>DS</sub>		Room		35		pF

Notes:
a. Refer to PROCESS OPTION FLOWCHART for additional information.
b. Room = 25 °C, Cold and Hot = as determined by the operating temperature suffix.
c. The algebraic convention whereby the most negative value is a minimum and the most positive a maximum, is used in this data sheet.
d. Typical values are for DESIGN AID ONLY, not guaranteed nor subject to production testing.
e. Guaranteed by design, not subject to production test.
f.  $C_{STRAY}$  Pin  $8 = \le 5$  pF.
g. Temperature coefficient of  $r_{DS(on)}$  is 0.75 % per °C, typical.

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#### **TIMING WAVEFORMS**



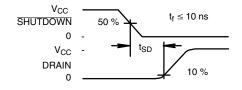


Figure 2.

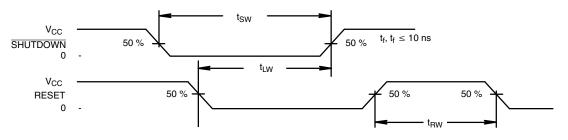


Figure 3.

#### **TYPICAL CHARACTERISTICS**

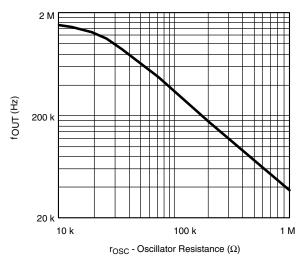
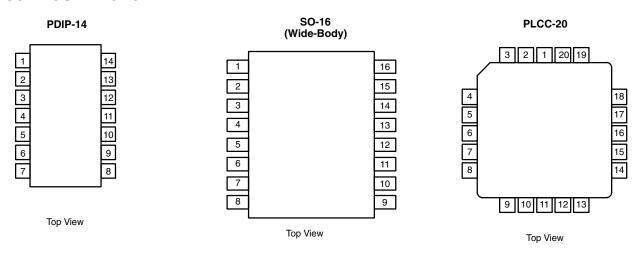


Figure 4. Output Switching Frequency vs. Oscillator Resistance



## **PIN CONFIGURATIONS**



N DESCRIPTION					
F		Pin Number			
Function	14-Pin Plastic DIP	16-Pin SOIC	20-Pin PLCC		
SOURCE	4	1	7		
- V <sub>IN</sub>	5	2	8		
V <sub>CC</sub>	6	4	9		
OSC <sub>OUT</sub>	7	5	10		
OSC <sub>IN</sub>	8	6	11		
DISCHARGE	9	7	12		
$V_{REF}$	10	8	14		
SHUTDOWN	11	9	16		
RESET	12	10	17		
COMP	13	11	18		
FB	14	12	20		
BIAS	1	13	2		
+V <sub>IN</sub>	2	14	3		
DRAIN	3	16	5		
NC		3, 15	1, 4, 6, 13, 15, 19		

ORDERING INFORMATION					
Standard Part Number	Lead (Pb)-free Part Number	Package	Temperature Range		
Si9108DJ02	Si9108DJ02-E3	PDIP-14			
Si9108DW			- 40 to 85 °C		
Si9108DW-T1	Si9108DW-T1-E3	SOIC-16 (WB)			
(With Tape and Reel)	(With Tape and Reel)				
Si9108DN02					
Si9108DN02-T1	Si9108DN02-T1-E3	PLCC-20			
(With Tape and Reel)	(With Tape and Reel)				

#### **DETAILED DESCRIPTION**

#### Pre-Regulator/Start-Up Section

Due to the low quiescent current requirement of the Si9108 control circuitry, bias power can be supplied from the unregulated input power source, from an external regulated low-voltage supply, or from an auxiliary "bootstrap" winding on the output inductor or transformer.

When power is first applied during start-up, +  $V_{IN}$  will draw a constant current. The magnitude of this current is determined by a high-voltage depletion MOSFET device which is connected between +  $V_{IN}$  and  $V_{CC}$ . This start-up circuitry provides initial power to the IC by charging an external bypass capacitance connected to the  $V_{CC}$  pin. The constant current is disabled when  $V_{CC}$  exceeds 9.3 V. If  $V_{CC}$  is not forced to exceed the 9.3 V threshold, then  $V_{CC}$  will be regulated to a nominal value of 9.3 V by the pre-regulator circuit.

As the supply voltage rises toward the normal operating conditions, an internal undervoltage (UV) lockout circuit keeps the output MOSFET disabled until  $V_{CC}$  exceeds the undervoltage lockout threshold (typically 8.7 V). This guarantees that the control logic will be functioning properly and that sufficient gate drive voltage is available before the MOSFET turns on. The design of the IC is such that the undervoltage lockout threshold will not exceed the pre-regulator turn-off voltage. Power dissipation can be minimized by providing an external power source to  $V_{CC}$  such that the constant current source is always disabled.

#### **BIAS**

To properly set the bias for the Si9108, a 820 k $\Omega$  resistor should be tied from BIAS to - V<sub>IN</sub>. This determines the magnitude of bias current in all of the analog sections and the pull-up current for the SHUTDOWN and RESET pins. The current flowing in the bias resistor is nominally 7.5  $\mu$ A.

#### **Reference Section**

The reference section of the Si9108 consists of a temperature compensated buried zener and trimmable divider network. The output of the reference section is connected internally to the non-inverting input of the error amplifier. Nominal reference output voltage is 4 V. The trimming procedure that is used on the Si9108 brings the output of the error amplifier (which is configured for unity gain during trimming) to within  $\pm$  1 % of 4 V. This automatically compensates for the input offset voltage in the error amplifier.

The output impedance of the reference section has been purposely made high so that a low impedance external voltage source can be used to override the internal voltage source, if desired, without otherwise altering the performance of the device.



#### **Error Amplifier**

Closed-loop regulation is provided by the error amplifier, whose 1  $k\Omega$  dynamic output impedance enables it to be used with feedback compensation (unlike transconductance amplifiers). A MOS differential input stage provides for low input current. The noninverting input to the error amplifier (V\_REF) is internally connected to the output of the reference supply and should be bypassed with a small capacitor to ground.

#### **Oscillator Section**

The oscillator consists of a ring of CMOS inverters, capacitors, and a capacitor discharge switch. Frequency is set by an external resistor between the OSC IN and OSC OUT pins. (See Typical Characteristics graph of resistor value vs. frequency.) The DISCHARGE pin should be tied to -V $_{\rm IN}$  for normal internal oscillator operation. For 98 % duty cycle, the discharge pin must be connected to - V $_{\rm IN}$  or can be connected to - V $_{\rm IN}$  through a resistor to set the dead time.

Remote synchronization can be accomplished by capacitive coupling of a synchronization pulse into the OSC IN terminal. For a 5 V pulse amplitude and 0.5  $\mu$ s pulse width, typical values would be 100 pF in series with 3  $\mu$  to OSC IN.

#### **SHUTDOWN** and RESET

SHUTDOWN and RESET are intended for overriding the output MOSFET switch via external control logic. The two inputs are fed through a latch preceding the output switch. Depending on the logic state of RESET, SHUTDOWN can be either a latched or unlatched input. The output is off whenever SHUTDOWN is low. By simultaneously having SHUTDOWN and RESET low, the latch is set and SHUTDOWN has no effect until RESET goes high. (See the table below.)

Table 1. Truth Table for the SHUTDOWN and RESET Pins

SHUTDOWN	RESET	Output		
Н	Н	Normal Operation		
Н	₹_	Normal Operation (No Change)		
L	Н	Off (Not Latched)		
L	L	Off (Latched)		
	L	Off (Latched, No Change)		

When power is first applied during start-up, +  $V_{IN}$  will draw a constant current. The magnitude of this current is determined by a high-voltage depletion MOSFET device which is connected between +  $V_{IN}$  and  $V_{CC}$ . This start-up circuitry provides initial power to the IC by charging an external bypass capacitance connected to the  $V_{CC}$  pin. The constant current is disabled when  $V_{CC}$  exceeds 9.3 V. If  $V_{CC}$  is not forced to exceed the 9.3 V threshold, then  $V_{CC}$  will be regulated to a nominal value of 9.3 V by the pre-regulator circuit.



#### **DETAIL DESCRIPTION (CONT'D)**

Both pins have internal current source pull-ups and can be left disconnected when not in use. An added feature of the current sources is the ability to connect a capacitor and an open-collector driver to the SHUTDOWN pin to provide variable shutdown time.

#### **Output Switch**

The output switch is a 7  $\Omega$  , 200 V lateral DMOS transistor. Like discrete MOSFETs, the switch contains an intrinsic body-drain diode. However, the body contact in the Si9108 is connected internally to -  $V_{\mbox{\footnotesize{IN}}}$  and is independent of the SOURCE.

#### **APPLICATIONS**

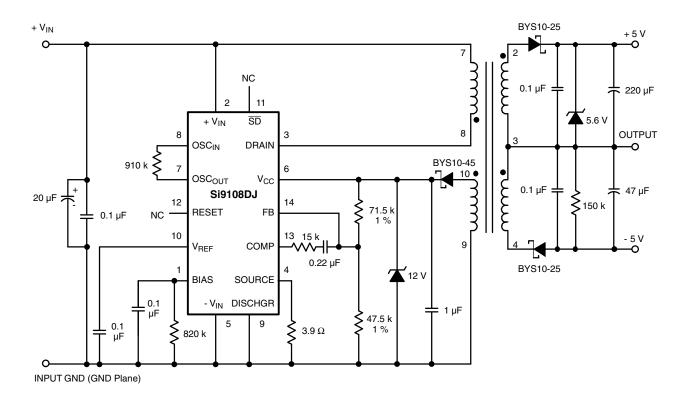
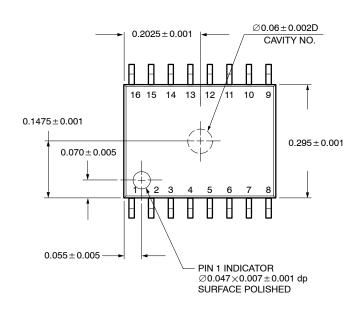


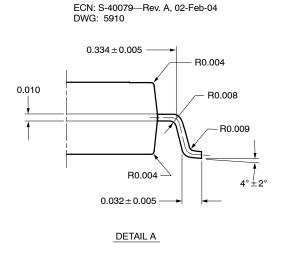
Figure 5. CCITT Compatible ISDN Terminal Power Supply

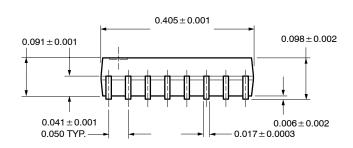
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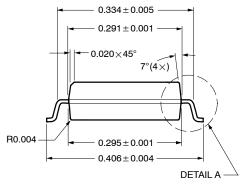


## SOIC (WIDE-BODY): 16-LEAD (POWER IC ONLY)





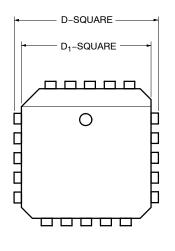


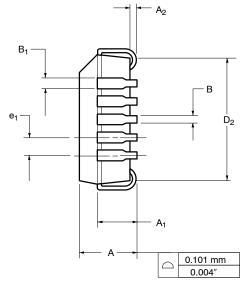


All Dimensions In Inches



## PLCC: 20-LEAD (POWER IC ONLY)

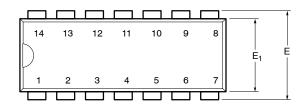


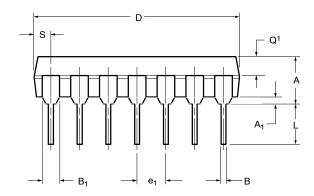


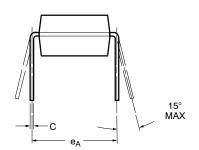
	MILLIN	IETERS	INC	HES	
Dim	Min	Max	Min	Max	
Α	4.20	4.57	0.165	0.180	
A <sub>1</sub>	2.29	3.04	0.090	0.120	
A <sub>2</sub>	0.51	-	0.020	-	
В	0.331	0.553	0.013	0.021	
B <sub>1</sub>	0.661	0.812	0.026	0.032	
D	9.78	10.03	0.385	0.395	
D <sub>1</sub>	8.890	9.042	0.350	0.356	
$D_2$	7.37	8.38	0.290	0.330	
e <sub>1</sub>	1.27 BSC 0.050 BSC				
ECN: S-40081—Rev. A, 02-Feb-04 DWG: 5917					



## PDIP: 14-LEAD (POWER IC ONLY)







	MILLIMETERS		INC	HES	
Dim	Min	Max	Min	Max	
Α	3.81	5.08	0.150	0.200	
A <sub>1</sub>	0.38	1.27	0.015	0.050	
В	0.38	0.51	0.015	0.020	
B <sub>1</sub>	0.89	1.65	0.035	0.065	
С	0.20	0.30	0.008	0.012	
D	17.27	19.30	0.680	0.760	
E	7.62	8.26	0.300	0.325	
E <sub>1</sub>	5.59	7.11	0.220	0.280	
e <sub>1</sub>	2.29	2.79	0.090	0.110	
e <sub>A</sub>	7.37	7.87	0.290	0.310	
L	2.79	3.81	0.110	0.150	
Q <sub>1</sub>	1.27	2.03	0.050	0.080	
S	1.02	2.03	0.040	0.080	
ECN: S-40081—Rev. A, 02-Feb-04 DWG: 5919					

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Revision: 02-Oct-12 Document Number: 91000